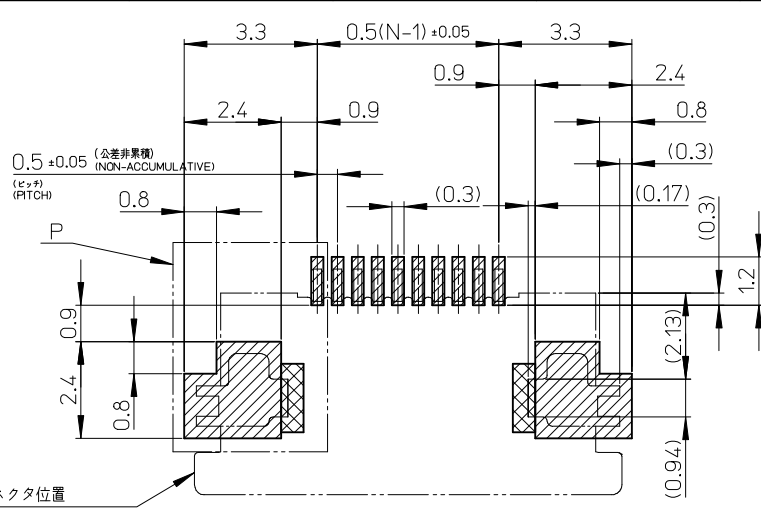


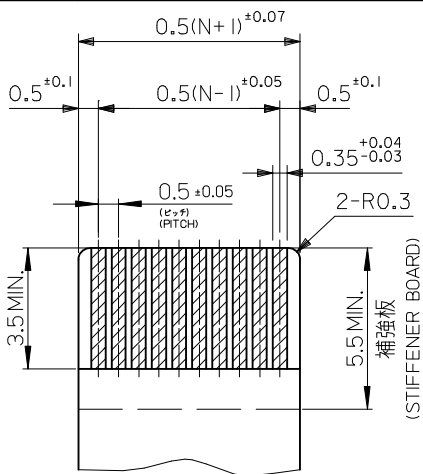
30.5	29.3	25.65	24.5	54132-5062	50
28.0	26.8	23.15	22.0	54132-4562	45
27.0	25.8	22.15	21.0	54132-4362	43
25.5	24.3	20.65	19.5	54132-4062	40
24.5	23.3	19.65	18.5	54132-3862	38
23.5	22.3	18.65	17.5	54132-3662	36
23.0	21.8	18.15	17.0	54132-3562	35
22.5	21.3	17.65	16.5	54132-3462	34
22.0	20.8	17.15	16.0	54132-3362	33
21.5	20.3	16.65	15.5	54132-3262	32
20.5	19.3	15.65	14.5	54132-3062	30
D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	CKT.

CONNECTOR SERIES NO. : 54132-**68

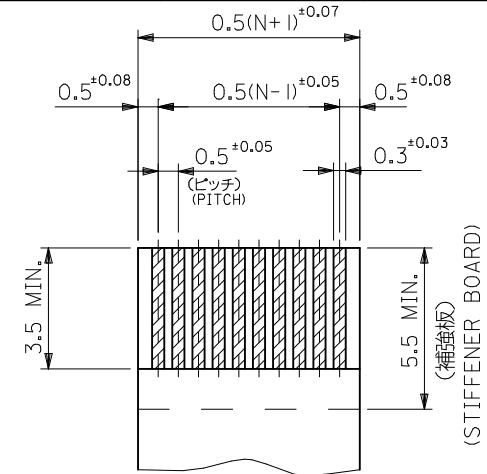
REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT NI-BARRIER GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064		
	ANGULAR ±3 °	MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



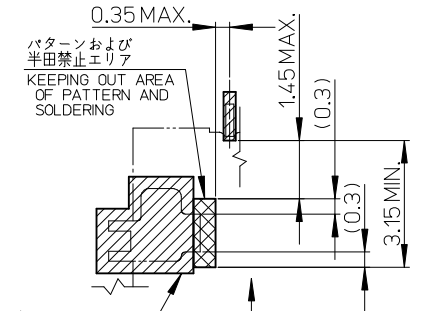
参考基板レイアウト
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)
(マウント面)
(MOUNTING SIDE)



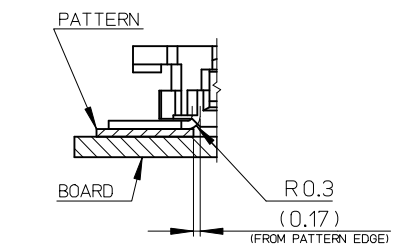
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)



適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD PLATING
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)



DETAIL P



VIEW R
(DETAIL OF FITTING NAIL ON PATTERN)

注記 NOTES

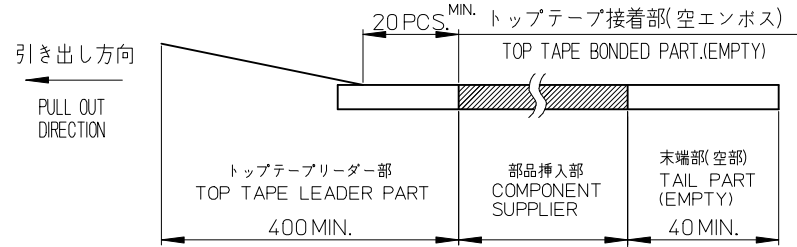
- 1.使用材料 MATERIAL
ハウジング : 46ナイロン、ガラス充填、UL94V-0、白
HOUSING:PA46,GLASS FILLED,UL94V-0,WHITE
アクチュエータ:ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR:POLYPHENYLENE SULFIDE,GLASS FILLED,UL94V-0,BLACK
ターミナル : リン青銅(=0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM
テール部 0.05 MICROMETER MINIMUM
ニッケル下地 1.0 MICROMETER MINIMUM
TERMINAL PHOS-BRONZE GOLD-PLATING
CONTACT PORTION : 0.1 MICROMETER MINIMUM
TAIL PORTION : 0.05 MICROMETER MINIMUM
NICKEL PLATING : 1.0 MICROMETER MINIMUM
金具 : リン青銅(=0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM
ニッケル下地 1.0~3.0 MICROMETER MINIMUM
FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM
OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
- 2.エンボステーパ梱包時はアクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54132-**68 SHOULD BE LOCKED.
ソルダータール半田付け面のズレ量、および金具半田付け面のズレ量は
基準面 \square に対し上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM \square
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはく離止め金具。
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.BOARD PATTERN.
- 6.本製品は54132-**61に対するニッケルバリア品になります。
THIS PRODUCT IS NICKEL-BARRIER OF 54132-**61.
- 7.ELV & RoHS適合品。
ELV AND ROHS COMPLIANT.
- FPC/FFCについて :
打ち抜き方向は導体側から補強板側を推奨いたします。
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします。
RECOMMENDED PUNCHER DIRECTION
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC
THICKNESS OF SOFT COPPER FOIL
: 35MICROMETERS OR 50MICROMETERS
- FPCについて :
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APP:R.KMORI/KAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT NI-BARRIER GOLD PLATING		
	10 OVER 30 UNDER	± ---	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY N.UKITA	DATE 2004/09/27	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-54132-064	SHEET NO. 2 OF 2
REV	ANGULAR	± --- °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

NOTE

- 1. 梱包数量 : 1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- 2. リードテープ長さ
LEAD TAPE LENGTH

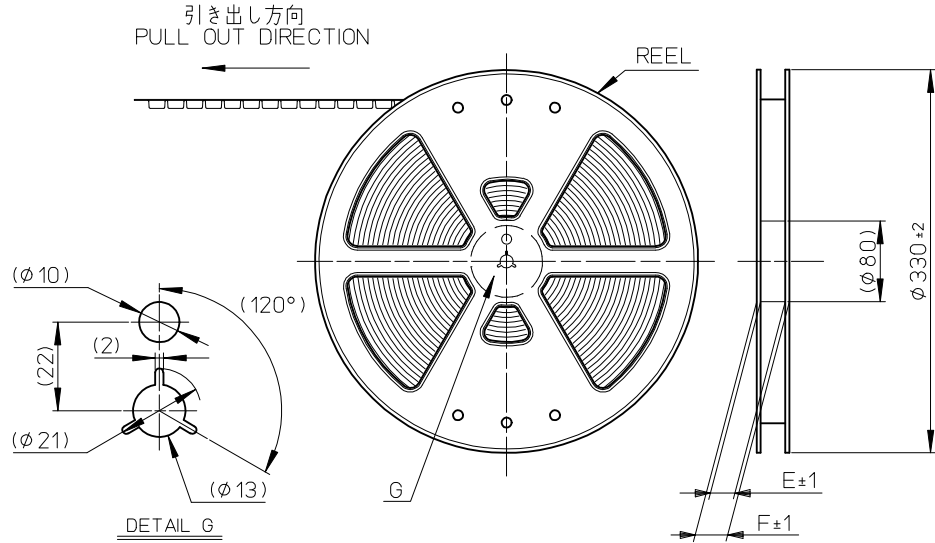


- 3. カバーテープの はく離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

- 4. 材料 キャリアテープ : ポリプロピレン(PP)
トップテープ : PET,PE,PEF
リール : ポリスチレン(PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE : POLYPROPYLENE
TOP TAPE : PET,PE,PEF
REEL : POLYSTYRENE<RECYCLE MATERIAL CONTAINED>

- 5. ELV & RoHS適合品
ELV AND RoHS COMPLIANT



RELEASED EC NO.: J2011-0041 DRWN: HYOSHINO 2010/07/13 CHKD: HIJIMA 2010/07/13 APPR: KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY HYOSHINO	DATE 2010/07/13	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT TAPING PACKAGE			
	10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA	DATE 2010/07/13	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/07/16	DOCUMENT NO. SD-54132-065		SHEET NO. 1 OF 2	
0	DESCRIPTION ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

